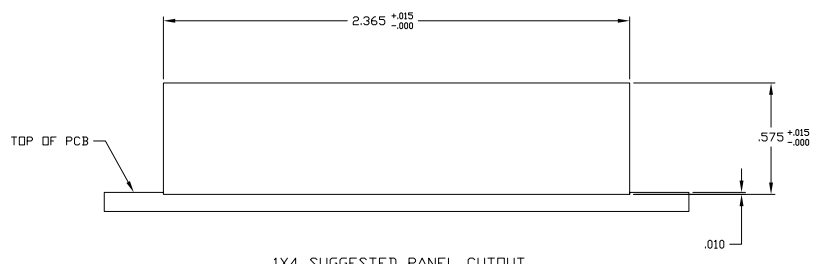
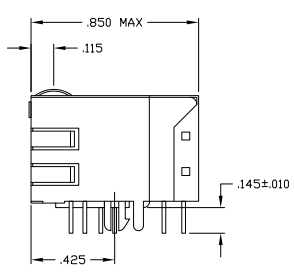
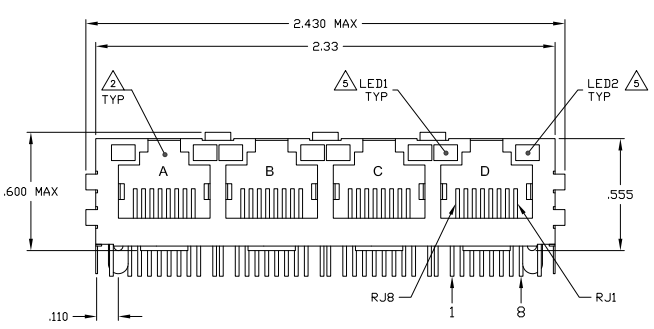
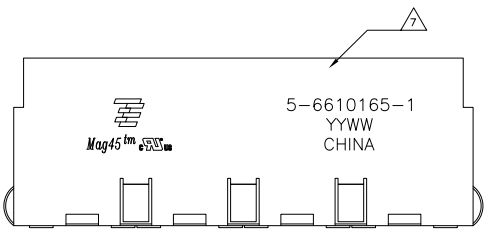


REV	DATE	DESCRIPTION	BY	CHK	APP
AA	22				
C		REV PER ECO-08-026524			RSE/2008 VL TX
C1		REVISED PER ECO-09-024927			110509 KK AEG

MECHANICAL:



1X4 SUGGESTED PANEL CUTOUT

- △ MATERIALS:
 - HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
 - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 - MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE.
 - SOLDER TAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
 - LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .027" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- △ RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
- △ MAGNETICS
 - IMPEDANCE 100 OHMS
 - TURNS RATIO (CHIP-CABLE): TX = 11, RX = 11
 - OPEN CIRCUIT INDUCTANCE (OCL): 350nH MIN @100kHz, 0 TVRMS.
 - 8mA DC BIAS FROM -40 C TO +85 C, TX AND RX
 - PERFORMANCE @ 25 C:
 - INSERTION LOSS (IL): 1.6dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 - 18-20LOG(F/30)dB MIN FROM 30.1MHz TO 60MHz
 - 12dB MIN FROM 60.1MHz TO 80MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 4.0MHz
 - 33-20LOG(F/50)dB MIN FROM 4.0MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 23.5.1.1, ITEM b.
- 4. OPERATING TEMPERATURE: FROM -40° C TO +85° C INDUSTRIAL TEMPERATURE.
- △ THE LED WITH 250 OHM RESISTORS, LED IS DRIVEN WITH 5V VOLTAGE AND THE MAX OPERATING CURRENT IS 20mA. LED COLOR - DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP. @ VF=5V
 FORWARD CURRENT (IF): GREEN 12 mA TYP. @ VF=5V
 DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP. @ VF=5V
 FORWARD CURRENT (IF): YELLOW 13 mA TYP. @ VF=5V
- △ INDICATED CONNECTIONS ARE FOR HUB CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL, AND SUPPORTS AUTO-MDI/MDIX.
- △ TYCO ELECTRONICS LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
- B. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS. PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS. PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

△ OBSOLETE	YELLOW	GREEN	5-6610165-2
	GREEN	YELLOW	5-6610165-1
	LED1	LED2	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	DATE	DESCRIPTION	BY	CHK	APP
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